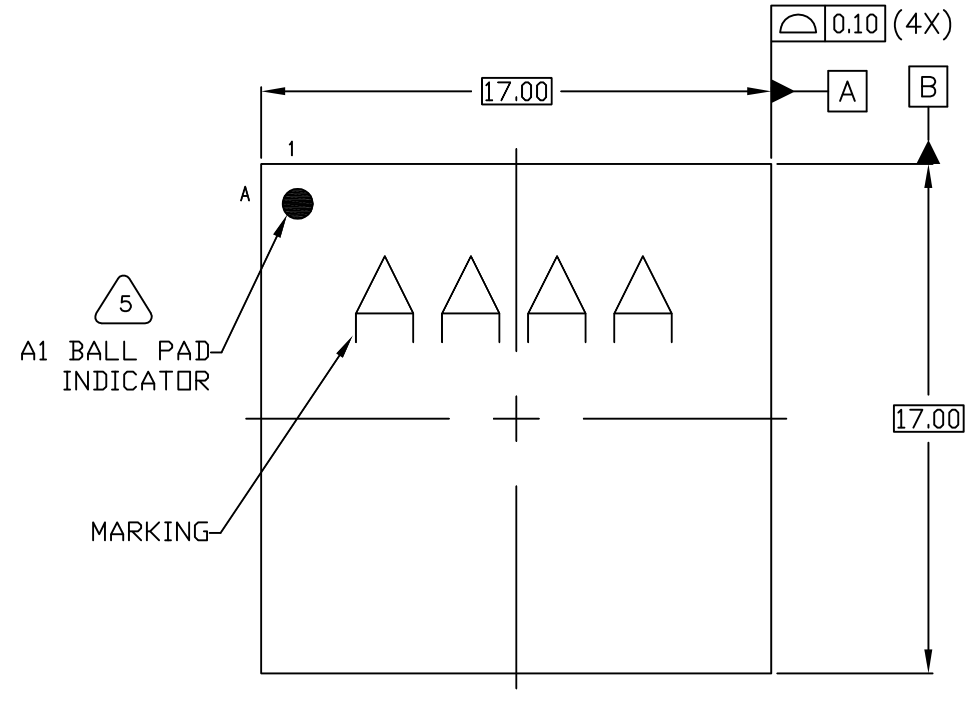
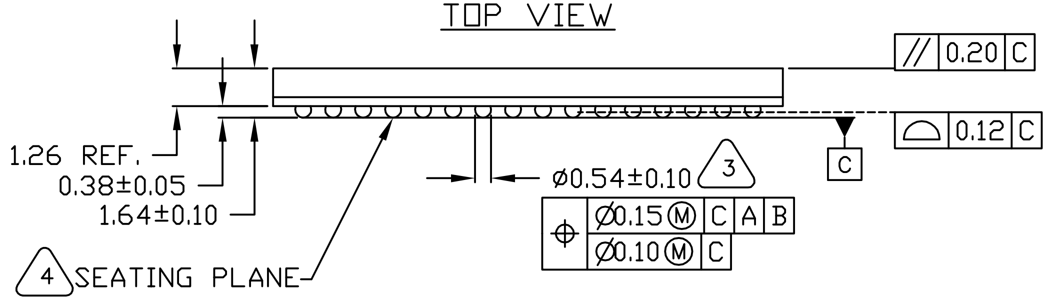
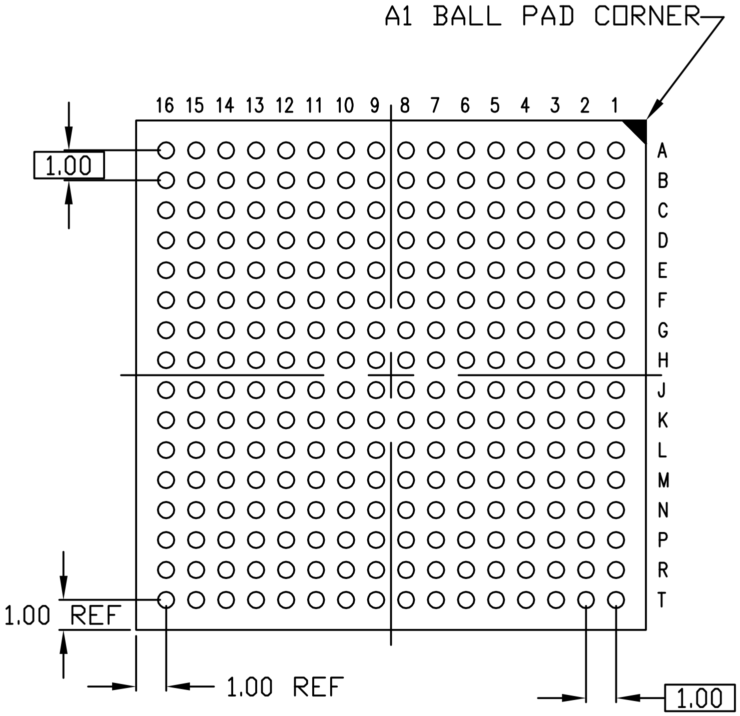


TOP VIEW



SIDE VIEW



BOTTOM VIEW
(BALL SIDE)

NOTES:

1. DIMENSION IS MM.
2. THE BASIC SOLDER BALL GRID PITCH IS 1.00 MM.
3. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. A1 BALL PAD CORNER I.D.
6. MARKING SHOWN IS FOR PACKAGE ORIENTATION REFERENCE ONLY.
7. ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PbFREE (+) PKG. CODES.
8. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC# 10-0131
9. PACKAGE CODES: X256-4

-DRAWING NOT TO SCALE-

TITLE:
PACKAGE OUTLINE,
256 BALLS CSBGA, 17x17mm

APPROVAL	DOCUMENT CONTROL NO.	REV.	
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